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APPLICANT

M. FUNABASHI

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GROUP

2825

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(Use several sheets if necessary)

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07/12/01

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AM	4,239,661	12/16/80	Muraoka et al.	438	252	541 471
	4,958,061	09/18/90	Wakabayashi et al.	219	411	
	5,286,678	02/15/94	Rastogi	438	437	200 301
	5,288,651	02/22/94	Nakazawa	438	437	31 145
	5,290,361	03/01/94	Hayashida et al.	134	2	
	5,447,568	09/05/95	Hayakawa et al.	118	437	187 715
	5,466,389	11/14/95	Ilardi et al.	510	252	456 175
	5,783,495	07/21/98	Li et al.	438	738	
	5,972,862	10/26/99	Torii et al.	510	175	
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Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
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	04-101418-A	04/1992	Japan	H01L	21/304		
	07-153728-A	06/1995	Japan	H01L	21/304		
	08-250461-A	09/1996	Japan	H01L	21/304		
	08-306650-A	11/1996	Japan	H01L	21/304		
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AM	AN	Oimet et al., "Defect Reduction and Cost Savings through Re-Inventing RCA Cleans", <i>IEEE/SEMI Advanced Semiconductor Manufacturing Conference</i> (1996), p. 308-313
	AO	Watanabe et al., "Influence of particles/impurity metals in RCA cleaning solutions on surface contamination", <i>International Symposium on Semiconductor Manufacturing</i> (1994), pp. 99-102
	AP	Osaka and Hattori, "Influence of Initial Wafer Cleanliness on Metal Removal Efficiency in Immersion SC-1 Cleaning: Limitation of Immersion-Type Wet Cleaning", <i>IEEE Trans. on Semiconductor Manufacturing</i> , Vol. 11, No. 1 (02/1998), pp. 20-24
	AQ	Ridley, Sr. et al., "Advanced Aqueous Wafer Cleaning in Power Semiconductor Device Manufacturing", <i>IEEE/SEMI Adv. Semiconductor Man. Conf.</i> (1998), pp. 235-242
	AR	"Improved Organic Clean for Removing Contaminants on Semiconductor Wafer Surfaces", <i>IBM Tech. Dis. Bulletin</i> , March 1985
AM	AS	"Improvements to MOS Retention Time Based Tests", <i>IBM Tech. Dis. Bulletin</i> , May 1984

Examiner

M. Funabashi

Date Considered

11-8-2001